TOSHIBA SG3000EX24

#### TOSHIBA GATE TURN-OFF THYRISTOR

# SG3000EX24

#### INVERTER APPLICATION

Repetitive Peak Off-State Voltage: V<sub>DRM</sub> = 2500 V

R.M.S On-State Current  $: I_{T(RMS)} = 1600 A$ 

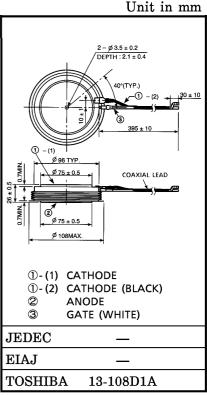
Peak Turn-Off Current  $: I_{TGQM} = 3000 A$ 

Critical Rate of Rise of On-State Current :  $di/dt = 400 \text{ A}/\mu \text{s}$ 

Critical Rate of Rise of Off-State Voltage :  $dv/dt = 1000 \text{ V}/\mu\text{s}$ 

### **MAXIMUM RATINGS**

CHARACTERISTIC	SYMBOL	RATING	UNIT	
Repetitive Peak Off-State Voltage (Note 1)	V <sub>DRM</sub> 2500		V	
Repetitive Peak Reverse Voltage	$v_{RRM}$	16	V	
Peak Turn-Off Current (Note 2)	$I_{\text{TGQM}}$	3000	Α	
R.M.S On-State Current (Note 3)	I <sub>T (RMS)</sub>	1600	A	
Peak One Cycle Surge On-State Current (Non Repetitive, 10 ms- Width Half Sine Waveform)	$I_{TSM}$	22000	A	
Critical Rate of Rise of On-State Current (Note 4)	di / dt	400	A/μs	
Peak Forward Gate Current	$I_{\text{FGM}}$	100	A	
Average Forward Gate Power Dissipation	P <sub>FG</sub> (AV)	50	w	
Average Reverse Gate Power Dissipation	P <sub>RG</sub> (AV)	150	w	
R.M.S Gate Current (Note 5)	I <sub>G</sub> (RMS)	42	A	
Peak Reverse Gate Voltage (at Static)	V <sub>RGM</sub>	16	v	
Operating Junction Temperature Range	Tj	-40~125	°C	
Storage Temperature Range	$T_{ m stg}$	-40~150	°C	
Mounting Force	_	$33.3 \pm 4.9$	kN	



Weight: 1290 g

(Note 1):  $V_{GK} = -2 V$ 

(Note 2) :  $V_{DM} = 2500 \,\mathrm{V}$ ,  $C_S = 6 \,\mu\mathrm{F}$ ,  $R_S = 5 \,\Omega$ ,  $\mathrm{di}_{GQ}/\mathrm{dt} = 30 \,\mathrm{A}/\mu\mathrm{s}$ ,  $V_{DSP} \le 750 \,\mathrm{V}$ ,

 $L_S \leq 0.2 \,\mu H$ 

(Note 3):  $50 \, \text{Hz}$  Half Sine Waveform at  $T_f = 75^{\circ}\text{C}$ 

(Note 4) :  $V_D = 1/2 V_{DRM}$ ,  $I_{GM} = 30 A$ 

(Note 5): Ambient Temperature of coaxial gate-cathode lead = 90°C

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## **ELECTRICAL CHARACTERISTICS**

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CHARACTERISTIC	SYMBOL	TEST CONDITION		MIN	TYP.	MAX	UNIT
Repetitive Peak Off-State Current	$I_{ m DRM}$	$V_{ m DRM} = { m Rated}, \ V_{ m GK} = -2  { m V},$ $T_{ m j} = 125 { m ^{\circ}C}$		_	_	100	mA
Repetitive Peak Reverse Current	$I_{RRM}$	$V_{ m RRM} = { m Rated}, \ T_{ m j} = 125 { m ^{\circ} C}$		_	_	10	mA
Repetitive Peak Reverse Gate Current	$I_{RGM}$	$V_{ m RGM} = 16   m V,  T_j = 125  m ^{\circ} C$		_	_	10	mA
Peak On-State Voltage	$V_{ extbf{TM}}$	$I_{TM} = 3000 \text{ A}, T_j = 125^{\circ}\text{C}$		_		3.0	V
Gate Trigger Voltage	$v_{GT}$		$T_j = -40^{\circ}C$	_	_	1.5	V
		$V_D = 24 V$	$T_j = 25^{\circ}C$			1.2	
Gate Trigger Current	$I_{\mathrm{GT}}$	$R_{L} = 0.1 \Omega$	$T_j = -40^{\circ}C$	_	_	10	A
			$T_j = 25^{\circ}C$	_	_	4.0	
Turn-On Delay Time	<sup>t</sup> d	$V_{D} = 1/2 V_{DRM},$ $I_{TM} = 3000 A,$		_	_	3.0	$\mu$ s
Turn-On Time	$t_{\mathrm{gt}}$	$egin{aligned} { m di/dt} &= 400\ { m A/} \mu{ m s}, \ { m I}_{ m GM} &= 30\ { m A},\ { m T}_{ m j} &= 25{ m ^{\circ}C} \end{aligned}$		_	_	10	μs
Critical Rate of Rise of Off- State Voltage	dv/dt	$V_{ m DRM} = 2/3$ RATED, Exponential Rise, $T_{ m j} = 125$ °C, $V_{ m GK} = -2$ V		1000	_	_	V/μs
Storage Time	$t_S$	$\begin{split} I_{TGQ} &= 3000 \text{ A, V}_{DM} = 2500 \text{ V,} \\ V_D &= 1/2 \text{ V}_{DRM}, \\ di_{GQ}/dt &= 30 \text{ A}/\mu\text{s,} \\ C_S &= 6 \mu\text{F, R}_S = 5 \Omega, \\ T_j &= 125 ^{\circ}\text{C, L}_S \leqq 0.2 \mu\text{H} \end{split}$		_	_	28	$\mu$ s
Gate Turn-Off Time	$t_{\mathrm{gq}}$			_	_	30	μs
Tail Time	t <sub>tail</sub>					90	μs
Gate Turn-Off Current	$I_{\mathbf{GQ}}$			_	650	_	A
Thermal Resistance (Junction to Fin)	R <sub>th (j-f)</sub>	DC		_	_	0.016	°C/W

